

### General Description

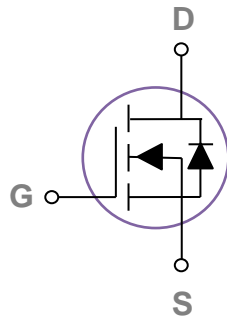
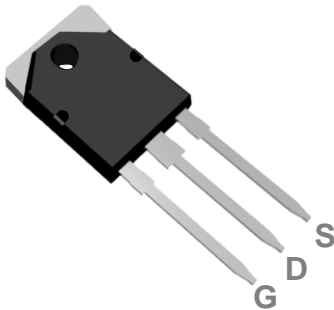
These N-Channel enhancement mode power field effect transistors are planar stripe, DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency switch mode power supply

BVDSS	RDSON	ID
900V	1.5Ω	9A

### Features

- 900V,9A,  $R_{DS(ON)} = 1.5\Omega @ V_{GS} = 10V$
- Improved  $dv/dt$  capability
- Fast switching
- 100% EAS Guaranteed
- Green Device Available

### TO-3P Pin Configuration



### Applications

- High efficient switched mode power supplies
- TV Power
- Adapter/charger
- LED Lighting

### Absolute Maximum Ratings $T_c=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	900	V
$V_{GS}$	Gate-Source Voltage	$\pm 30$	V
$I_D$	Drain Current – Continuous ( $T_c=25^\circ\text{C}$ )	9	A
	Drain Current – Continuous ( $T_c=100^\circ\text{C}$ )	5.7	A
$I_{DM}$	Drain Current – Pulsed <sup>1</sup>	36	A
EAS	Single Pulse Avalanche Energy <sup>2</sup>	230	mJ
IAS	Single Pulse Avalanche Current <sup>2</sup>	6.8	A
$P_D$	Power Dissipation ( $T_c=25^\circ\text{C}$ )	347	W
	Power Dissipation – Derate above $25^\circ\text{C}$	2.78	W/ $^\circ\text{C}$
$T_{STG}$	Storage Temperature Range	-55 to 150	$^\circ\text{C}$
$T_J$	Operating Junction Temperature Range	-55 to 150	$^\circ\text{C}$

### Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction to ambient	---	62	$^\circ\text{C/W}$
$R_{\theta JC}$	Thermal Resistance Junction to Case	---	0.36	$^\circ\text{C/W}$

**Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)**
**Off Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =250uA	900	---	---	V
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =900V , V <sub>GS</sub> =0V , T <sub>J</sub> =25°C	---	---	1	uA
		V <sub>DS</sub> =720V , V <sub>GS</sub> =0V , T <sub>J</sub> =100°C	---	---	20	uA
I <sub>GSS</sub>	Gate-Source Leakage Current	V <sub>GS</sub> =±30V , V <sub>DS</sub> =0V	---	---	±100	nA

**On Characteristics**

R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> =10V , I <sub>D</sub> =4.5A	---	1.2	1.5	Ω
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250uA	3	4	5	V
gfs	Forward Transconductance	V <sub>DS</sub> =30V , I <sub>D</sub> =3A	---	6	---	S

**Dynamic and switching Characteristics**

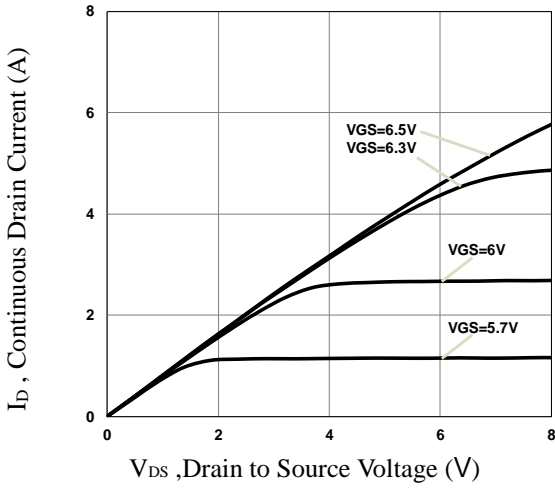
Q <sub>g</sub>	Total Gate Charge <sup>3,4</sup>	V <sub>DS</sub> =450V , V <sub>GS</sub> =10V , I <sub>D</sub> =4.5A	---	43	65	nC
Q <sub>gs</sub>	Gate-Source Charge <sup>3,4</sup>		---	13	20	
Q <sub>gd</sub>	Gate-Drain Charge <sup>3,4</sup>		---	23	35	
T <sub>d(on)</sub>	Turn-On Delay Time <sup>3,4</sup>	V <sub>DD</sub> =450V , V <sub>GS</sub> =10V , R <sub>G</sub> =25Ω I <sub>D</sub> =4.5A	---	50	75	ns
T <sub>r</sub>	Rise Time <sup>3,4</sup>		---	65	100	
T <sub>d(off)</sub>	Turn-Off Delay Time <sup>3,4</sup>		---	86	130	
T <sub>f</sub>	Fall Time <sup>3,4</sup>		---	34	50	
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =25V , V <sub>GS</sub> =0V , F=1MHz	---	1980	2970	pF
C <sub>oss</sub>	Output Capacitance		---	145	220	
C <sub>rss</sub>	Reverse Transfer Capacitance		---	6.5	10	
R <sub>g</sub>	Gate resistance	V <sub>GS</sub> =0V , V <sub>DS</sub> =0V , F=1MHz	---	1.4	---	Ω

**Drain-Source Diode Characteristics and Maximum Ratings**

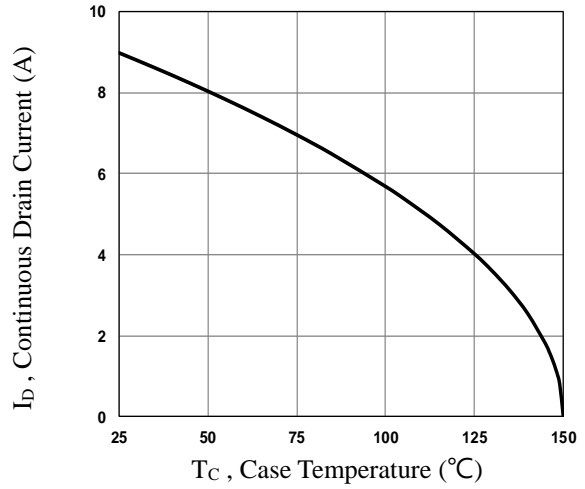
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I <sub>S</sub>	Continuous Source Current	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current	---	---	9	A
I <sub>SM</sub>	Pulsed Source Current		---	---	18	A
V <sub>SD</sub>	Diode Forward Voltage	V <sub>GS</sub> =0V , I <sub>S</sub> =4.5A , T <sub>J</sub> =25°C	---	---	1.3	V
t <sub>rr</sub>	Reverse Recovery Time <sup>3</sup>	V <sub>R</sub> =400V , I <sub>S</sub> =5A	---	505	---	ns
Q <sub>rr</sub>	Reverse Recovery Charge <sup>3</sup>	di/dt=100A/μs , T <sub>J</sub> =25°C	---	6.3	---	uC

Note :

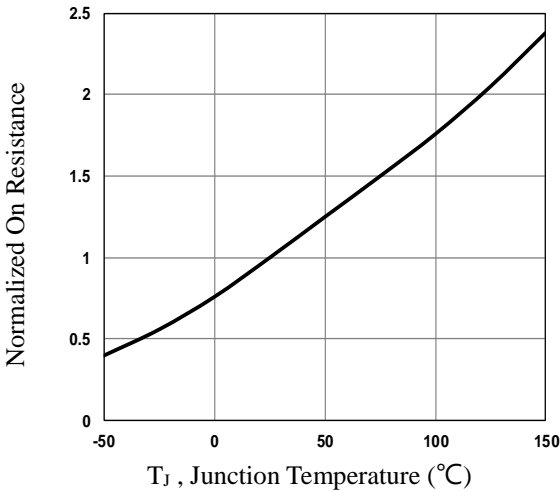
1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. V<sub>DD</sub>=100V, V<sub>GS</sub>=10V, L=10mH, I<sub>AS</sub>=6.8A., R<sub>G</sub>=25Ω, Starting T<sub>J</sub>=25°C.
3. The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%.
4. Essentially independent of operating temperature.



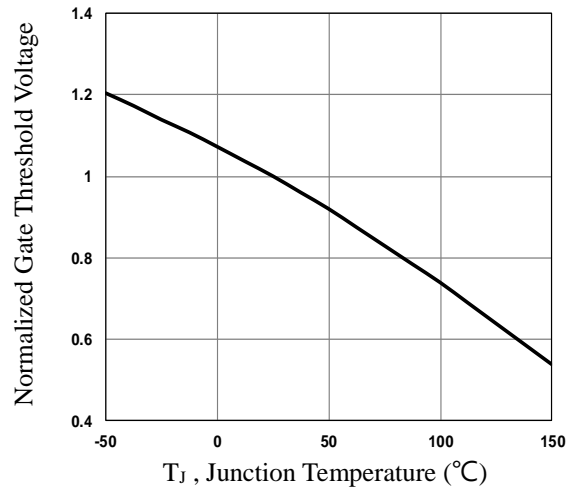
**Fig.1 Typical Output Characteristics**



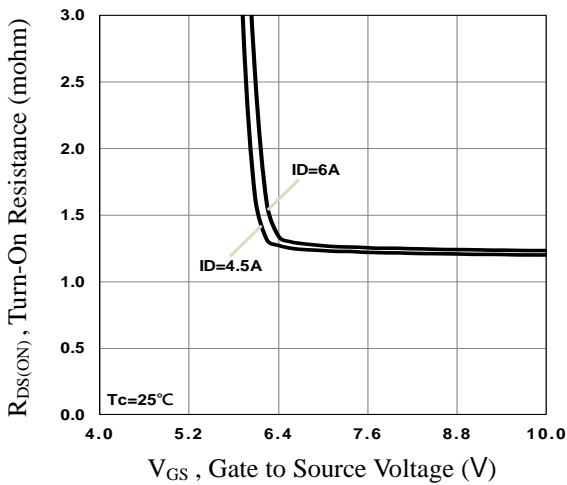
**Fig.2 Continuous Drain Current vs. T<sub>c</sub>**



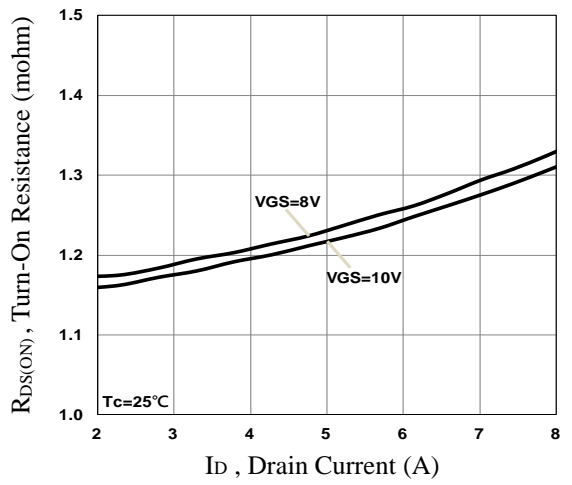
**Fig.3 Normalized R<sub>DS(on)</sub> vs. T<sub>J</sub>**



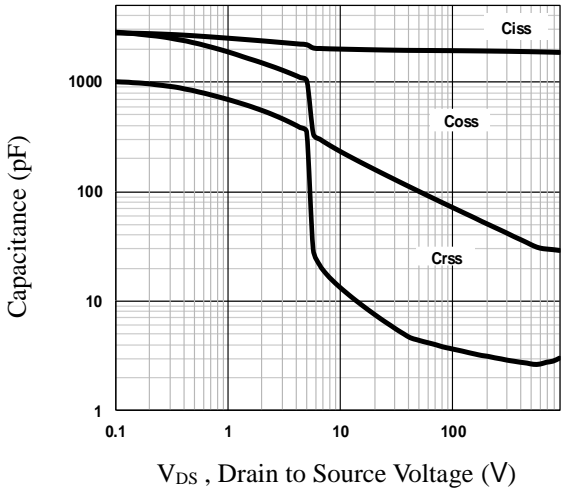
**Fig.4 Normalized V<sub>th</sub> vs. T<sub>J</sub>**



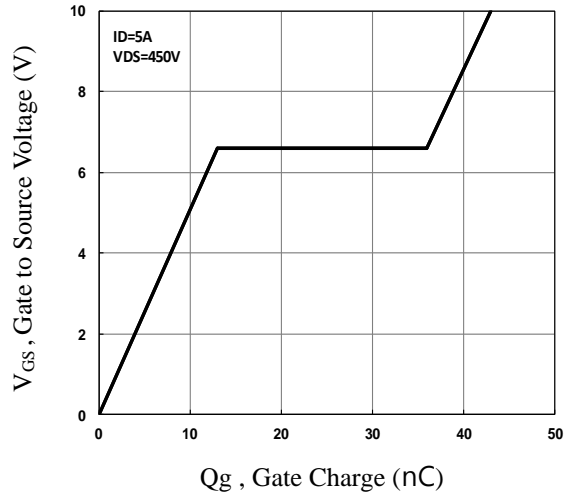
**Fig.5 Turn-On Resistance vs. V<sub>GS</sub>**



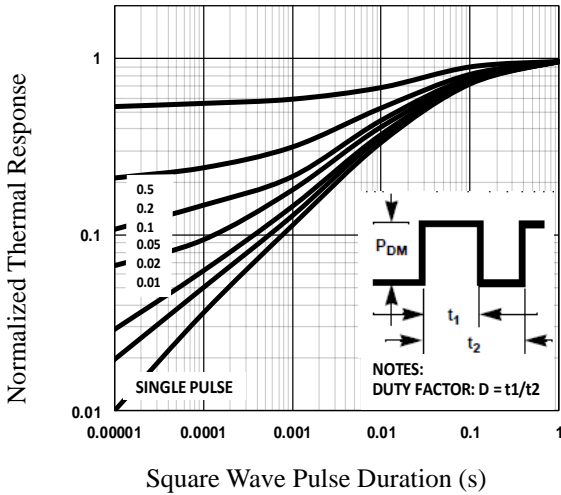
**Fig.6 Turn-On Resistance vs. I<sub>D</sub>**



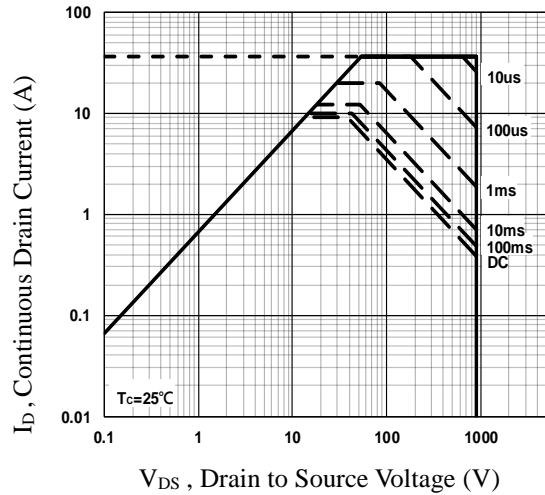
**Fig.7 Capacitance Characteristics**



**Fig.8 Gate Charge Characteristics**



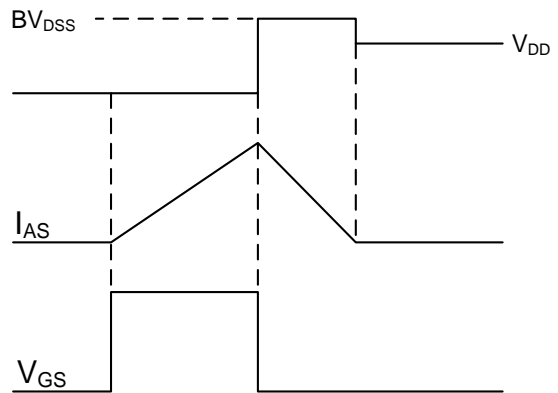
**Fig.9 Normalized Transient Impedance**



**Fig.10 Maximum Safe Operation Area**

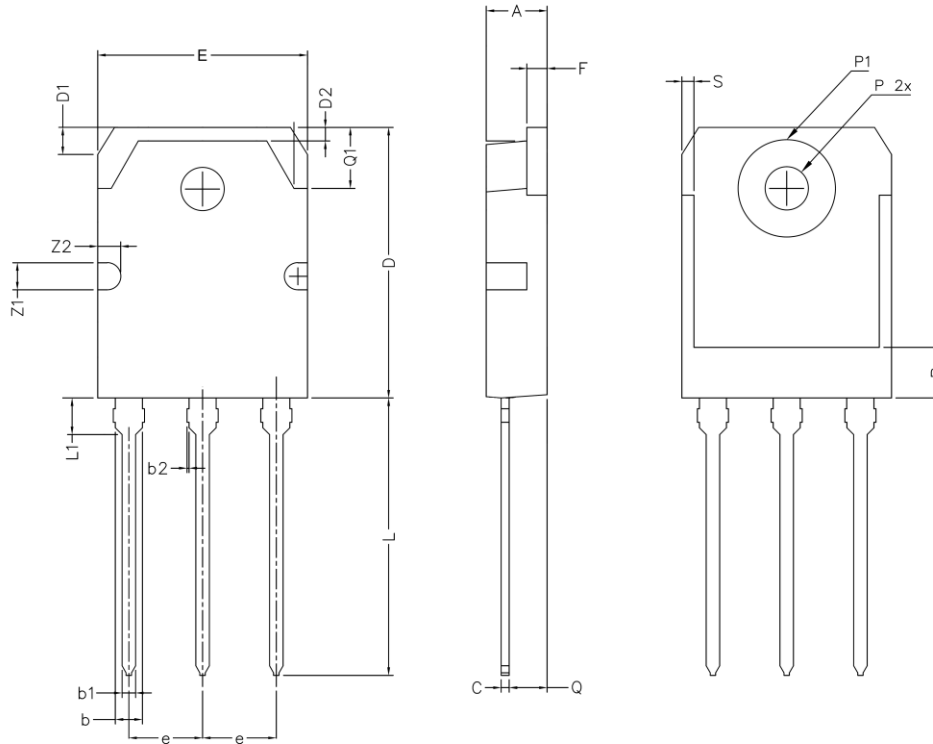


**Fig.11 Switching Time Waveform**



**Fig.12 EAS Waveform**

## TO-3P PACKAGE INFORMATION



SYMBOL	mm		SYMBOL	mm	
	MIN	MAX		MIN	MAX
A	4.300	4.700	L1	2.100	3.300
b	1.700	2.300	P	3.000	3.400
b1	0.750	1.300	P1	7.200 REF	
b2	---	0.200	R	3.74 REF	
C	0.500	0.900	S	0.900 REF	
D	19.70	20.30	Q	2.600	3.000
D1	1.500	2.500	Q1	4.300	4.700
D2	0.700	1.300	Z1	1.700	2.300
E	15.20	15.80	Z2	1.400	2.000
F	1.300	1.700			
e	5.45 BSC				
L	20.00	21.00			